

SOT1496-1

plastic thin fine-pitch ball grid array package; 144 balls

21 April 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA
Package type industry code	TFBGA144
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	21-4-2016

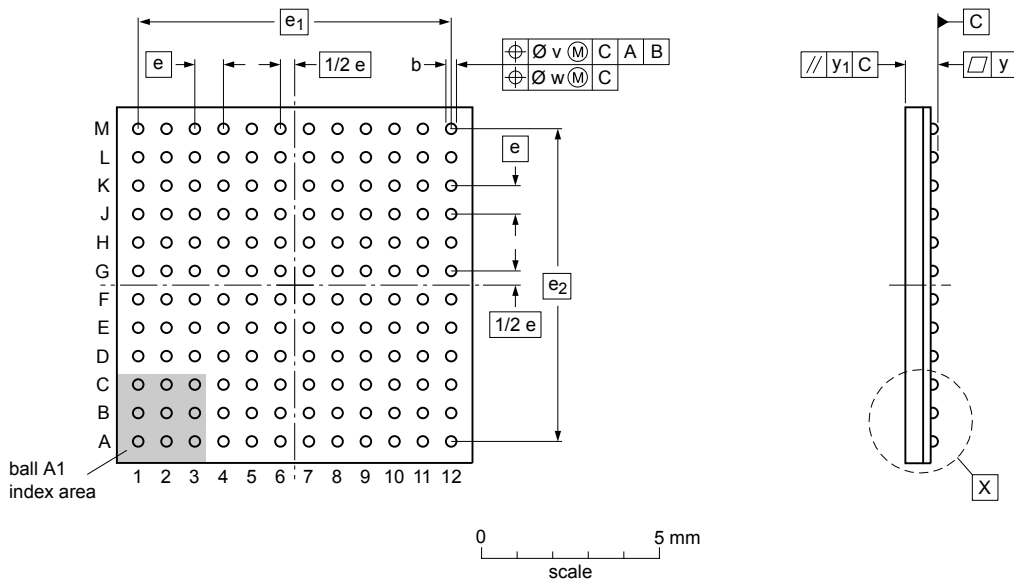
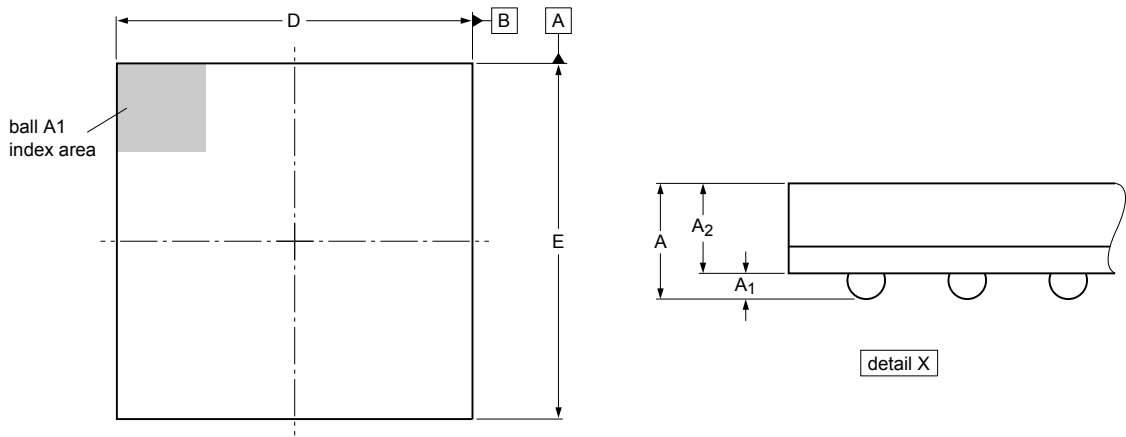
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.9	-	10	10.1	mm
E	package width	9.9	-	10	10.1	mm
A	seated height	-	-	0.92	1.06	mm
A ₂	package height	0.62	-	0.71	0.8	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	144	-	



2. Package outline

TFBGA144: plastic thin fine-pitch ball grid array package; 144 balls SOT1496-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	1.06	0.26	0.80	0.35	10.1	10.1							
nom	0.92	0.21	0.71	0.30	10.0	10.0	0.8	8.8	8.8	0.15	0.05	0.08	0.1
min	---	0.16	0.62	0.25	9.9	9.9							

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1496-1	---	---	---		-15-11-26- 15-12-08

Fig. 1. Package outline TFBGA144 (SOT1496-1)

3. Legal information

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